

UNISONIC TECHNOLOGIES CO., LTD

3N50-CB Preliminary Power MOSFET

3A, 500V N-CHANNEL POWER MOSFET

■ DESCRIPTION

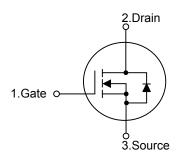
The UTC **3N50-CB** is an N-channel mode power MOSFET using UTC's advanced technology to provide customers with planar stripe and DMOS technology. This technology allows a minimum on-state resistance and superior switching performance. It also can withstand high energy pulse in the avalanche and commutation mode.

The UTC **3N50-CB** is generally applied in high efficiency switch mode power supplies, active power factor correction and electronic lamp ballasts based on half bridge topology.

■ FEATURES

- * $R_{DS(ON)}$ < 3.0 Ω @ V_{GS} = 10V, I_{D} = 1.5A
- * High Switching Speed
- * 100% Avalanche Tested

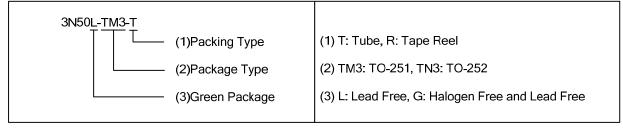




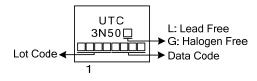
ORDERING INFORMATION

Ordering Number		Dookogo	Pin Assignment			Dooking	
Lead Free	Halogen Free	Package	1	2	3	Packing	
3N50L-TM3-T	3N50G-TM3-T	TO-251	G	D	S	Tube	
3N50L-TN3-R	3N50G-TN3-R	TO-252	G	D	S	Tape Reel	

Note: Pin Assignment: G: Gate D: Drain S: Source



■ MARKING



TO-251

www.unisonic.com.tw 1 of 6

■ **ABSOLUTE MAXIMUM RATINGS** (T_C=25°C, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT	
Drain-Source Voltage		V_{DSS}	500	V	
Gate-Source Voltage		V_{GSS}	±30	V	
Drain Current	Continuous (T _C =25°C)	I_{D}	3 (Note 5)	Α	
	Pulsed (Note 2)	I_{DM}	12 (Note 5)	Α	
Avalanche Current (Note 2)		I_{AR}	3	Α	
Avalanche Energy	Single Pulsed (Note 3)	E _{AS}	58	mJ	
Peak Diode Recovery dv/dt (Note 4)		dv/dt	1.3	V/ns	
Power Dissipation (T _C =25°C)		P _D	50	W	
Derate above 25°C			0.4	W/°C	
Power Dissipation		0	36	W	
Derate above 25°C		P_D	0.288	W/°C	
Junction Temperature		TJ	+150	°C	
Storage Temperature		T _{STG}	-55~+150	°C	

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

- 2. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 3. L = 13 mH, I_{AS} = 3A, V_{DD} = 50V, R_G = 25 Ω , Starting T_J = 25 $^{\circ}$ C
- 4. $I_{SD} \le 3A$, di/dt $\le 200A/\mu s$, $V_{DD} \le BV_{DSS}$, Starting $T_J = 25^{\circ}C$
- 5. Drain current limited by maximum junction temperature.

■ THERMAL DATA

PARAMETER	SYMBOL	RATINGS	UNIT
Junction to Ambient	θ_{JA}	110	°C/W
Junction to Case	$\theta_{ m JC}$	2.5	°C/W

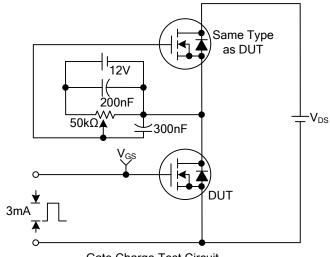
■ **ELECTRICAL CHARACTERISTICS** (T_C=25°C, unless otherwise noted)

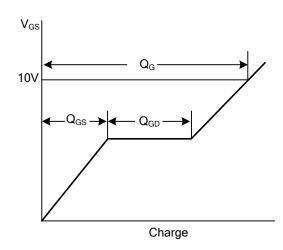
PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS			•				
Drain-Source Breakdown Voltage		BV _{DSS}	I _D =250μA, V _{GS} =0V				V
Drain-Source Leakage Current		I _{DSS}	V _{DS} =500V, V _{GS} =0V			1	μA
Gate- Source Leakage Current	Forward	I _{GSS}	V_{GS} =+30V, V_{DS} =0V			+100	nA
	Reverse		V_{GS} =-30V, V_{DS} =0V			-100	nA
ON CHARACTERISTICS							
Gate Threshold Voltage		$V_{GS(TH)}$	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	2.0		4.0	V
Static Drain-Source On-State Resistance		R _{DS(ON)}	V _{GS} =10V, I _D =1.5A			3.0	Ω
DYNAMIC PARAMETERS		_				ā.	-
Input Capacitance		C_{ISS}			230		pF
Output Capacitance		Coss	V _{GS} =0V, V _{DS} =25V, f=1.0MHz		43		pF
Reverse Transfer Capacitance		C_{RSS}	1		6.3		pF
SWITCHING PARAMETERS							
Total Gate Charge		Q_{G}	\/ -F0\/ \/ -10\/ -1.2A		19		nC
Gate to Source Charge		Q_GS	V _{DS} =50V, V _{GS} =10V, I _D =1.3A , I _G =100μA (Note 1, 2)		2.0		nC
Gate to Drain Charge		Q_GD	IG-100μΑ (Note 1, 2)		1.0		nC
Turn-ON Delay Time		$t_{D(ON)}$			30		ns
Rise Time		t_R	V_{DD} =30V, V_{GS} =10V, I_{D} =0.5A, R_{G} =25 Ω (Note 1, 2)		20		ns
Turn-OFF Delay Time		t _{D(OFF)}			80		ns
Fall-Time		t_{F}			30		ns
SOURCE- DRAIN DIODE RATIN	NGS AND (CHARACTERI	STICS			-	-
Drain-Source Diode Forward Voltage		V_{SD}	V_{GS} =0V, I_{S} =3A			1.4	V
Maximum Body-Diode Continuous Current		Is				3	Α
Maximum Body-Diode Pulsed Current		I _{SM}				12	Α
Reverse Recovery Time		t _{rr}	V _{GS} =0V, I _S =3A		270		ns
Reverse Recovery Charge		Q_{RR}	dI _F /dt=100A/μs (Note 1)		1.0		μC

Notes: 1. Pulse Test: Pulse width ≤ 300µs, Duty cycle ≤ 2%

^{2.} Essentially independent of operating temperature

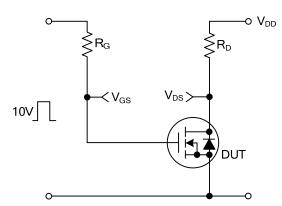
TEST CIRCUITS AND WAVEFORMS

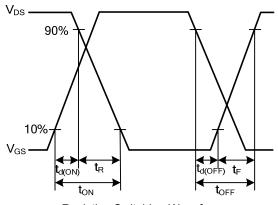




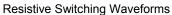
Gate Charge Test Circuit

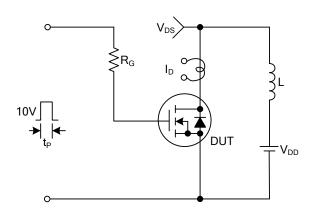
Gate Charge Waveforms

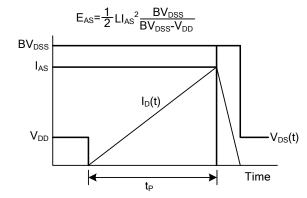




Resistive Switching Test Circuit



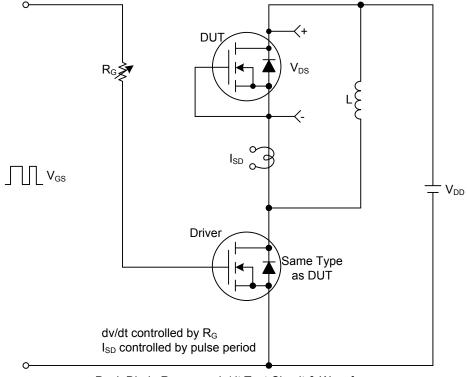




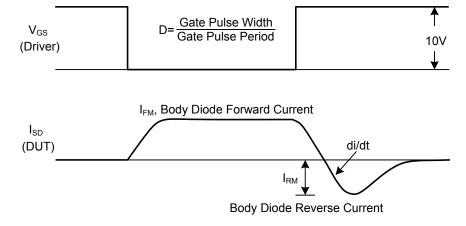
Unclamped Inductive Switching Test Circuit

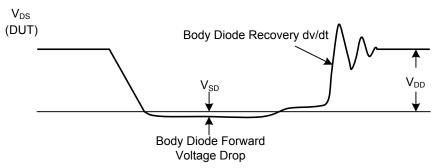
Unclamped Inductive Switching Waveforms

■ TEST CIRCUITS AND WAVEFORMS(Cont.)



Peak Diode Recovery dv/dt Test Circuit & Waveforms





UTC assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all UTC products described or contained herein. UTC products are not designed for use in life support appliances, devices or systems where malfunction of these products can be reasonably expected to result in personal injury. Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner. The information presented in this document does not form part of any quotation or contract, is believed to be accurate and reliable and may be changed without notice.

